IPC ASSOCIATION CO ELECTRONICS IN	© Copyright 2005. I	Material Composition Declaration Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both nternational and Pan-American copyright conventions.		The level of the l	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				erials and Mfg Info	als and Mfg Information			
upplier Ir	nformation													
Company name*			Company unique ID			Uı	nique ID Autho	rity		Response Date	Response Date*			
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Authorized Representative*			Title - Representative			Pł	Phone - Representative*			Email - Repres	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			N	NA			Product-Env-	Product-Env-Stewards@onsemi.com			
Ro	Requester Item Number		Mfr Item Number Mfr Item Name			E	Effective Date	Version	Manufacturing Site	Weight	* UOM	Unit Type		
		AFGY10	GY100T65SPD FS3 IGBT 650V/100A Diode		100A and Auto Ste	ealth 2	025-07-02		CPA	5544.59	) mg	Each		
lanufactu	uring Proccess Informa	tion												
Те	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 MSI		J-STD-020 MSL R	Rating	Peak Process Body Temperature Max Time at Peal			Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0	C	30	seconds 3					

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its part and the supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedi										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temper	erature type solders (i.e. lead based solder	alloys containing 85% by weight or more lead).								
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	12.65	mg	Supplier	Silicon (Si)	7440-21-3		12.65	mg
Die Attach Solder	20.87	mg	Supplier	Silver (Ag)	7440-22-4		0.5218	mg
			A	Lead (Pb)	7439-92-1	7a	19.3048	mg
			Supplier	Tin (Sn)	7440-31-5		1.0435	mg
Lead Frame	3643.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.4576	mg
			В	Nickel (Ni)	7440-02-0		119.1555	mg
			Supplier	Iron (Fe)	7439-89-6		2.1863	mg
			Supplier	Copper (Cu)	7440-50-8		3520.0071	mg
			Supplier	Phosphorus (P)	7723-14-0		1.0932	mg
Mold Compound-Black	1759.15	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		87.9575	mg
			Supplier	Proprietary	Proprietary Data		87.9575	mg
			Supplier	Carbon Black (C)	1333-86-4		8.7957	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		79.1618	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1319.3625	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		87.9575	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		87.9574	mg
Plating	77.82	mg	Supplier	Tin (Sn)	7440-31-5		77.82	mg
Wire Bond - Al	30.2	mg	Supplier	Aluminum (Al)	7429-90-5		30.2	mg